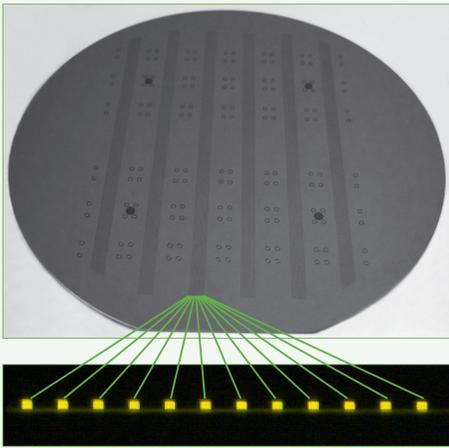
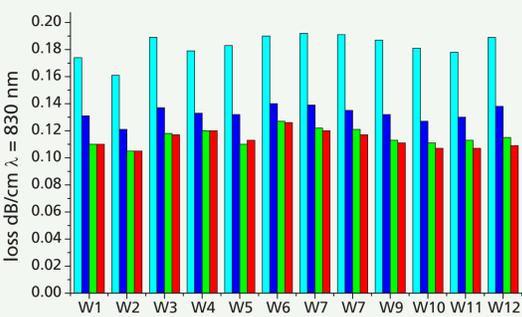


# EpoCore & EpoClad - Negative Tone Photoresist Series

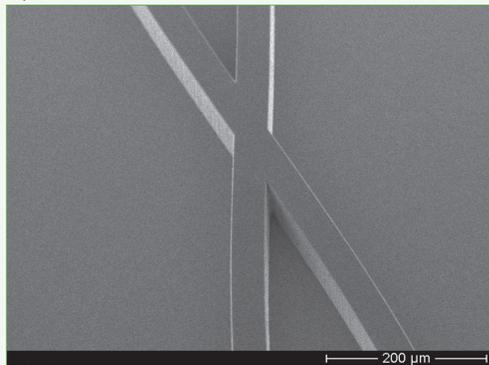
For manufacture of optical single mode (SM) & multi mode (MM) waveguides



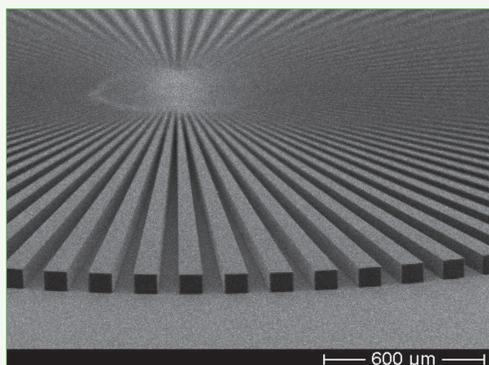
EpoCore/ EpoClad waveguides



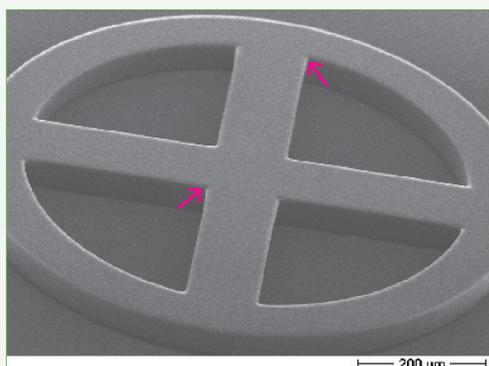
after:  
 Lamination 185 °C 23.5 kp/cm<sup>2</sup>  
 Reflow 3 x 230 °C  
 TCT 100 x -40/125 °C  
 TCT 204 x -40/125 °C  
 Optical loss after lamination and TCT



40 µm EpoCore structure



40 µm EpoCore, sun structure



EpoCore pattern, no microcracks on critical spots

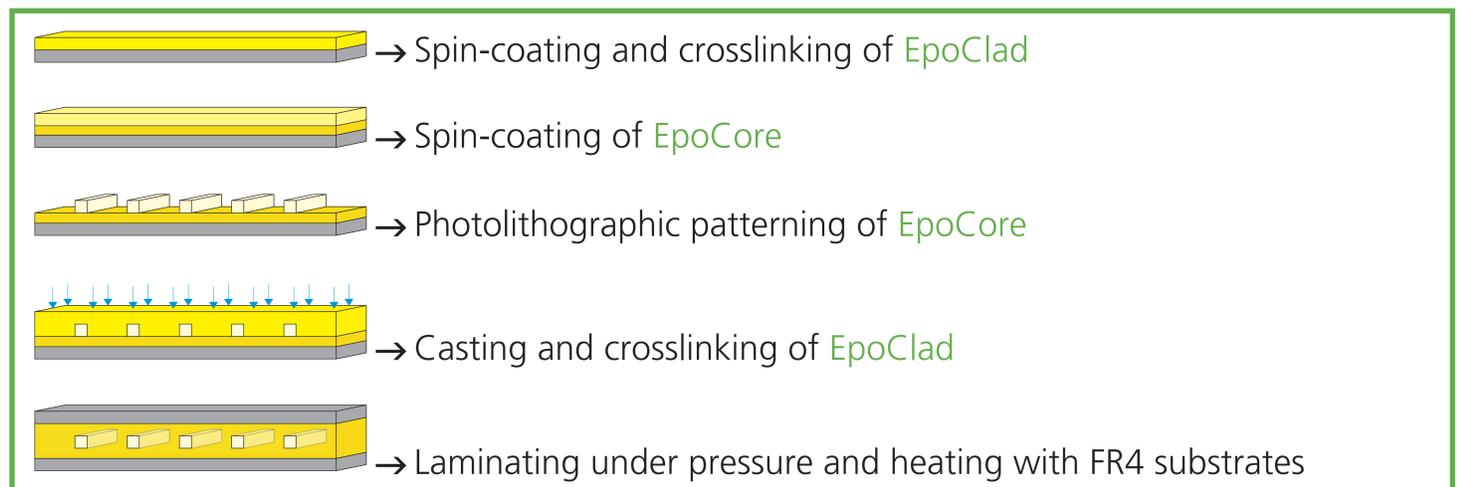
## Unique features

- Standard UV lithography & PCB technology processing
- UV patterning of core and cladding
- High transmittance @ 850 nm
- High heat (> 230 °C) and pressure resistance

## Applications

- Optical SM & MM waveguides
- Beam splitters
- Biosensors (multifunctional systems)

## Process flow



## Technical data

Resist	EpoCore	EpoClad
Spectral sensitivity	Broadband, 365 nm	
Ready-to-use solutions for various film thicknesses from 1.5 µm to 120 µm	EpoCore 2 EpoCore 5 EpoCore 10 EpoCore 20 EpoCore 50	EpoClad 2 EpoClad 5 EpoClad 10 EpoClad 20 EpoClad 50
Developer	mr-Dev 600 (solvent based)	
<b>Properties of cured resist</b>		
Shrinkage	< 3 %	
Thermal stability	up to 230 °C	
Refractive index @ 830 nm	1.58	1.57
Optical loss	~ 0.2 dB/cm @ 850 nm	
Glass transition temperature	> 180 °C	
Excellent stability after lamination	T > 185°C, pressure 23 kp/cm <sup>2</sup> and reflow tests 3 x 15 s @ 230 °C, TCT: 240 x -40 °C to 120 °C	

